

TECHNICAL SPECIFICATION	ENAVISION 250
OVERVIEW	
Build Envelop Volume (mm ³) Range of Layer Thickness Feature Thickness Laser Type Laser Power Scanning Speed Scanning System Dimension (LxWxH) Electrical Connection (Voltage) Electrical Connection (Current) Inert Gas O2 Level Vacuum Pump Operating System Network Build Plate Temperature	250X250X300 (9,8x9,8x11,8 in) 20-100 μm (0,0007 - 0,004 in) 150 μm Fiber laser 500 W (Single Mode) Up to 11 m/S (433,07 in) 3D dynamic focused scanning system 2700x1440x2030 (106,3x56,7x79,9 in) 460 V, 3 PH, 60 Hz 32 A Argon / Nitrogen <100 ppm Yes Windows 10 / X Ethernet / Ethercat 0- 200 °C
OPTICAL SCANNING SYSTEM	
Scanning Speed Scanning System Cooling System	Up to 11 m/S (433,07 in) 3D dynamic focused scanning system Water
CONTROL UNIT	
Ccontrol System Processor Operating System HMI	Beckhoff Industrial PC Intel i5-i7 Windows 10 / X 21.5 in, touch operated
SOFTWARE	
Data Preparation Software Data Processing Software Supported File Types	Materiliase Magics and Modules Ermaksan Build Processor STL , 3MF, AMF,, DAE , FBX, VRML ...
FEATURES	
Beam Focus Diameter/Beam Diameter	100 μm
Beam Correction	Auto
Recoater blade	Silicon
Dimensional accuracy	± 100 μm
Surface roughness	Ra<20μm
Relative Density of as printed parts	≥99%
Process Monitoring Camera	HD Camera to follow the building process
Quality Comformation	CE

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